# 83940D

# RENESAS Low Skew, 1-to-18 LVPECL-TO-LVCMOS / LVTTL Fanout Buffer

### DATASHEET

## **GENERAL DESCRIPTION**

The 83940D is a low skew, 1-to-18 LVPECL-to-LVC-MOS/LVTTL Fanout Buffer. The 83940D has two selectable clock inputs. The PCLK, nPCLK pair can accept LVPECL, CML, or SSTL input levels. The LVCMOS\_ CLK can accept LVCMOS or LVTTL input levels. The low impedance LVCMOS/LVTTL outputs are designed to drive  $50\Omega$ series or parallel terminated transmission lines.

The 83940D is characterized at full 3.3V and 2.5V or mixed3.3V core, 2.5V output operating supply modes. Guaranteed output and part-to-part skew characteristics make the 83940D ideal for those clock distribution applications demanding well defined performance and repeatability.

### **F**EATURES

- 18 LVCMOS/LVTTL outputs
- Selectable LVCMOS\_CLK or LVPECL clock inputs
- PCLK, nPCLK supports the following input types: LVPECL, CML, SSTL
- LVCMOS\_CLK accepts the following input levels: LVCMOS or LVTTL
- Maximum output frequency: 250MHz
- Output skew: 150ps (maximum)
- · Part to part skew: 750ps (maximum)
- Additive phase jitter, RMS: < 0.03ps (typical)</li>
- Full 3.3V and 2.5V or mixed 3.3V core, 2.5V output supply modes
- 0°C to 70°C ambient operating temperature
- Lead-Free package available

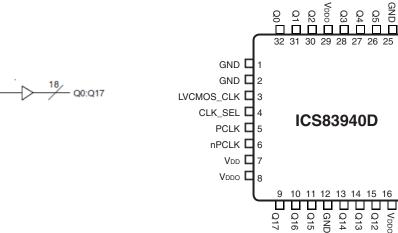
## **BLOCK DIAGRAM**

CLK\_SEL

nPCI k

LVCMOS\_CLK

## **PIN ASSIGNMENT**





ND

24 🗖 Q6

23 🗖 Q7

22 🗖 Q8

20 🗖 Q9

19 🗖 Q10

18 🗖 Q11

17 GND

21

🛛 VDD

#### TABLE 1. PIN DESCRIPTIONS

Number	Name	Т	уре	Description
1, 2, 12, 17, 25	GND	Power		Power supply ground.
3	LVCMOS_CLK	Input	Pulldown	Clock input. LVCMOS / LVTTL interface levels.
4	CLK_SEL	Input	Pulldown	Clock select input. Selects LVCMOS / LVTTL clock input when HIGH. Selects PCLK, nPCLK inputs when LOW. LVCMOS / LVTTL interface levels.
5	PCLK	Input	Pulldown	Non-inverting differential LVPECL clock input.
6	nPCLK	Input	Pullup/ Pulldown	Inverting differential LVPECL clock input. $V_{DD}$ /2 default when left floating.
7, 21	V <sub>DD</sub>	Power		Core supply pins.
8, 16, 29	V <sub>DDO</sub>	Power		Output supply pins.
9, 10, 11, 13, 14, 15, 18, 19, 20, 22, 23, 24, 26, 27, 28, 30, 31, 32	Q17, Q16, Q15, Q14, Q13, Q12, Q11, Q10, Q9, Q8, Q7, Q6, Q5, Q4, Q3, Q2, Q1, Q0	Output		Clock outputs. LVCMOS / LVTTL interface levels.

NOTE: Pullup and Pulldown refers to internal input resistors. See Table 2, Pin Characteristics, for typical values.

#### TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
C <sub>PD</sub>	Power Dissipation Capacitance (per output)			6		pF
R <sub>PULLup</sub>	Input Pullup Resistor			51		KΩ
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		KΩ
R <sub>out</sub>	Output Impedance		18		28	Ω

#### TABLE 3A. CLOCK SELECT FUNCTION TABLE

Control Input	Clock			
CLK_SEL	PCLK, nPCLK	LVCMOS_CLK		
0	Selected	De-selected		
1	De-selected	Selected		

#### TABLE 3B. CLOCK INPUT FUNCTION TABLE

	Ing	outs		Outputs	Innut to Output Mode	Delerity
CLK_SEL	LVCMOS_CLK	PCLK	nPCLK	Q0:Q17	Input to Output Mode	Polarity
0	—	0	1	LOW	Differential to Single Ended	Non Inverting
0	—	1	0	HIGH	Differential to Single Ended	Non Inverting
0	_	0	Biased; NOTE 1	LOW	Single Ended to Single Ended	Non Inverting
0	_	1	Biased; NOTE 1	HIGH	Single Ended to Single Ended	Non Inverting
0	—	Biased; NOTE 1	0	HIGH	Single Ended to Single Ended	Inverting
0	—	Biased; NOTE 1	1	LOW	Single Ended to Single Ended	Inverting
1	0	—	—	LOW	Single Ended to Single Ended	Non Inverting
1	1	—	—	HIGH	Single Ended to Single Ended	Non Inverting

NOTE 1: Please refer to the Application Information section, "Wiring the Differential Input to Accept Single Ended Levels".

#### ABSOLUTE MAXIMUM RATINGS

Supply Voltage, $V_{DD}$	3.6V
Inputs, V <sub>I</sub>	-0.3V to $V_{DD}$ + 0.3V
Outputs, V <sub>o</sub>	-0.3V to $V_{\text{DDO}}$ + 0.3V
Input Current, I <sub>IN</sub>	±20mA
Storage Temperature, $T_{_{STG}}$	-40°C to 125°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V <sub>IH</sub>	Input High Voltage	LVCMOS_CLK		2.4		V <sub>DD</sub>	V
V <sub>IL</sub>	Input Low Voltage	LVCMOS_CLK				0.8	V
V <sub>PP</sub>	Peak-to-Peak Input Voltage	PCLK, nPCLK		500		1000	mV
V <sub>CMR</sub>	Input Common Mode Voltage; NOTE 1, 2	PCLK, nPCLK		V <sub>DD</sub> - 1.4		V <sub>DD</sub> - 0.6	V
I <sub>IN</sub>	Input Current					±200	μA
V <sub>OH</sub>	Output High Voltage		I <sub>он</sub> = -20mA	2.4			V
V <sub>ol</sub>	Output Low Voltage		I <sub>oL</sub> = 20mA			0.5	V
I <sub>DD</sub>	Core Supply Current					25	mA

#### TABLE 4A. DC Characteristics, $V_{DD} = V_{DDO} = 3.3V \pm 5\%$ , TA = 0° to 70°

NOTE 1: For single ended applications, the maximum input voltage for PCLK, nPCLK is  $V_{DD}$  + 0.3V.

NOTE 2: Common mode voltage is defined as  $V_{H}$ .

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency						MHz
	Dropogation Dalay	PCLK, nPCLK; NOTE 1, 5	$f \leq 150 MHz$	1.6		3.0	ns
t <sub>pLH</sub>	Propagation Delay	LVCMOS_CLK; NOTE 2, 5	$f \leq 150 MHz$	1.8		3.0	ns
	Dropogation Dalay	PCLK, nPCLK; NOTE 1, 5	f > 150MHz	1.6		250       3.0       3.0       3.0       3.0       3.3       3.2       150       150       1.4       1.2       1.7       1.4       850       750       0.03       1.1	ns
t <sub>pLH</sub>	Propagation Delay	on Delay LVCMOS_CLK; f > 150MHz NOTE 2, 5	1.8		3.2	ns	
	Output Skew;	PCLK, nPCLK	Measured on			3.0         3.3         3.2         150         150         1.4         1.2         1.7         1.4         850         750	ps
tsk(o)	NOTE 3, 5	LVCMOS_CLK	rising edge @V <sub>DDO</sub> /2			150	ps
t = 1 = ( = = = )	Part-to-Part Skew;	PCLK, nPCLK	f ≤ 150MHz			3.2 150 150 1.4 1.2 1.7 1.4	ns
tsk(pp)	NOTE 6	LVCMOS_CLK	f ≤ 150MHz			1.2	ns
t = 1 = ( = = = )	Part-to-Part Skew;	PCLK, nPCLK	f > 150MHz			1.7	ns
tsk(pp)	NOTE 6	LVCMOS_CLK	f > 150MHz			1.4	ns
tol/mm)	Part-to-Part Skew;	PCLK, nPCLK	Measured on			850	ps
tsk(pp)	NOTE 4, 5	LVCMOS_CLK	rising edge @V <sub>DDO</sub> /2			750	ps
tjit	NOTE 6 LVCMOS_CLK Part-to-Part Skew; PCLK, nPCLK				0.03		ps
t <sub>R</sub> /t <sub>F</sub>	Output Rise/Fall Tim	ie	0.5 to 2.4V	0.3		1.1	ns
			f < 134MHz	45	50	55	%
odc	Output Duty Cycle		$134MHz \le f \le 250MHz$	40	50	250 3.0 3.0 3.3 3.2 150 1.4 1.2 1.7 1.4 850 750 1.1	%

All parameters measured at 200MHz unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the output  $V_{DDO}/2$ .

NOTE 2: Measured from  $V_{DD}/2$  to  $V_{DDO}/2$ .

NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at  $V_{_{DDO}}/2$ . NOTE 4: Defined as skew between outputs on different devices operating at the same supply voltages, same temperature, and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at  $V_{_{DDO}}/2$ .

NOTE 5: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 6: Defined as skew between outputs on different devices, across temperature and voltage ranges, and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at  $V_{DDO}/2$ .

NOTE 7: Driving only one input clock.

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V <sub>IH</sub>	Input High Voltage	LVCMOS_CLK		2.4		V <sub>DD</sub>	V
V <sub>IL</sub>	Input Low Voltage	LVCMOS_CLK				0.8	V
V <sub>PP</sub>	Peak-to-Peak Input Voltage	PCLK, nPCLK		300		1000	mV
V <sub>CMR</sub>	Input Common Mode Voltage; NOTE 1, 2	PCLK, nPCLK		V <sub>DD</sub> - 1.4		V <sub>DD</sub> - 0.6	V
I <sub>IN</sub>	Input Current					±200	μA
V <sub>OH</sub>	Output High Voltage		I <sub>он</sub> = -20mA	1.8			V
V <sub>ol</sub>	Output Low Voltage		I <sub>oL</sub> = 20mA			0.5	V
I <sub>DD</sub>	Core Supply Current					25	mA

#### TABLE 4B. DC CHARACTERISTICS, $V_{DD} = 3.3V \pm 5\%$ , $V_{DDO} = 2.5V \pm 5\%$ , TA = 0° to 70°

NOTE 1: For single ended applications, the maximum input voltage for PCLK, nPCLK is V<sub>DD</sub> + 0.3V.

NOTE 2: Common mode voltage is defined as V<sub>III</sub>.

Table 5B. AC Characteristics, $V_{DD} = 3.3V \pm 5\%$	$V_{\text{DDO}} = 2.5 \text{V} \pm 5\%, \text{TA} = 0^{\circ} \text{ to } 70^{\circ}$	)°
Symbol Parameter	Test Conditions	Minimum

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency					250	MHz
+	Propagation Dolay	the product of the product product of the product of	ns				
t <sub>pLH</sub>	FTOPAGALIOIT Delay	/	$f \le 150 MHz$	1.7		3.0	ns
+	Propagation Delay		f > 150MHz	1.6		3.2         3.0         3.4         3.3         150         150         1.5         1.3         1.8         1.5         850	ns
t <sub>pLH</sub>	Propagation Delay		f > 150MHz	1.8		3.3	ns
tok(o)	Output Skew;	PCLK, nPCLK	Measured on			250 3.2 3.0 3.4 3.3 150 150 1.5 1.3 1.8 1.8 1.5 850 750	ps
tsk(o)	NOTE 3, 5	LVCMOS_CLK	rising edge @V <sub>DDO</sub> /2			150	ps
tel(mm)	Part-to-Part Skew;	PCLK, nPCLK	f ≤ 150MHz			1.5	ns
tsk(pp)	NOTE 6	LVCMOS_CLK	f ≤ 150MHz			1.3	ns
t = 1 - ( -= -= )	Part-to-Part Skew;	PCLK, nPCLK	f > 150MHz			1.8	ns
tsk(pp)	NOTE 6	LVCMOS_CLK	f > 150MHz			1.5	ns
tok(nn)	Part-to-Part Skew;	PCLK, nPCLK	Measured on			850	ps
tsk(pp)	NOTE 4, 5	LVCMOS_CLK	rising edge @V <sub>DDO</sub> /2			750	ps
tjit					0.03		ps
t <sub>R</sub> /t <sub>F</sub>	Output Rise/Fall Tin	ne	0.5 to 1.8V	0.3		1.2	ns
odc	Output Duty Cycle		f < 134MHz	45	50	55	%

All parameters measured at 200MHz unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the output  $V_{DDO}/2$ .

NOTE 2: Measured from  $V_{DD}/2$  to  $V_{DDO}/2$ .

NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at  $V_{DDO}/2$ . NOTE 4: Defined as skew between outputs on different devices operating at the same supply voltages, same temperature, and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at  $V_{DDO}/2$ .

NOTE 5: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 6: Defined as skew between outputs on different devices, across temperature and voltage ranges, and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at  $V_{DDO}/2$ .

NOTE 7: Driving only one input clock.

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V <sub>IH</sub>	Input High Voltage	LVCMOS_CLK		2		V <sub>DD</sub>	V
V <sub>IL</sub>	Input Low Voltage	LVCMOS_CLK				0.8	V
V <sub>pp</sub>	Peak-to-Peak Input Voltage	PCLK, nPCLK		300		1000	mV
V <sub>cmr</sub>	Input Common Mode Voltage; NOTE 1, 2	PCLK, nPCLK		V <sub>DD</sub> - 1.4		V <sub>DD</sub> - 0.6	V
I <sub>IN</sub>	Input Current					±200	μA
V <sub>oh</sub>	Output High Voltage		I <sub>он</sub> = -12mA	1.8			V
V <sub>ol</sub>	Output Low Voltage		I <sub>oL</sub> = 12mA			0.5	V
I <sub>DD</sub>	Core Supply Current					25	mA

#### TABLE 4C. DC Characteristics, $V_{DD} = V_{DDO} = 2.5V \pm 5\%$ , TA = 0° to 70°

NOTE 1: For single ended applications, the maximum input voltage for PCLK, nPCLK is  $V_{DD}$  + 0.3V.

NOTE 2: Common mode voltage is defined as  $V_{\mu}$ .

#### TABLE 5C. AC Characteristics, $V_{DD} = V_{DDO} = 2.5V \pm 5\%$ , TA = 0° to 70°

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency					200	MHz
t <sub>pLH</sub>	Propagation Delay;	PCLK, nPCLK; NOTE 1, 5	f ≤ 150MHz	1.2		3.8	ns
		LVCMOS_CLK; NOTE 2, 5	f ≤ 150MHz	1.5		3.2	ns
t <sub>pLH</sub>	Propagation Delay;	PCLK, nPCLK; NOTE 1, 5	f > 150MHz	1.5		3.7	ns
		LVCMOS_CLK; NOTE 2, 5	f > 150MHz	2		3.6	ns
tsk(o)	Output Skew; NOTE 3, 5	PCLK, nPCLK	Measured on rising edge @V <sub>DDO</sub> /2			200	ps
		LVCMOS_CLK				200	ps
tsk(pp)	Part-to-Part Skew; NOTE 6	PCLK, nPCLK	f ≤ 150MHz			2.6	ns
		LVCMOS_CLK	f ≤ 150MHz			1.7	ns
tsk(pp)	Part-to-Part Skew; NOTE 6	PCLK, nPCLK	f > 150MHz			2.2	ns
		LVCMOS_CLK	f > 150MHz			1.7	ns
tsk(pp)	Part-to-Part Skew; NOTE 4, 5	PCLK, nPCLK	Measured on			1.2	ns
		LVCMOS_CLK	rising edge @V <sub>DDO</sub> /2			1.0	ns
tjit	Buffer Additive Phase Jitter, RMS; refer to Additive Phase Jitter section, NOTE 7				0.03		ps
t <sub>R</sub> /t <sub>F</sub>	Output Rise/Fall Time		0.5 to 1.8V	0.3		1.2	ns
odc	Output Duty Cycle		f < 134MHz	45		55	%

All parameters measured at 200MHz unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the output  $V_{DDO}/2$ .

NOTE 2: Measured from  $V_{DD}/2$  to  $V_{DDD}/2$ . NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at  $V_{DDD}/2$ . NOTE 4: Defined as skew between outputs on different devices operating at the same supply voltages, same temperature,

and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at V<sub>onc</sub>/2.

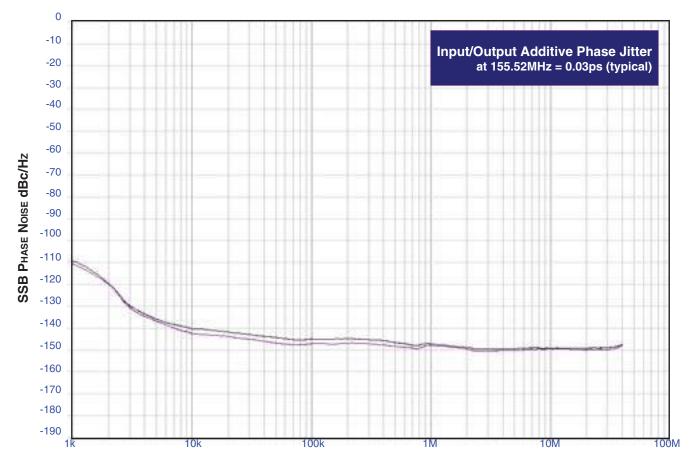
NOTE 5: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 6: Defined as skew between outputs on different devices, across temperature and voltage ranges,

and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at  $V_{\text{DDO}}/2$ . NOTE 7 Driving only one input clock.

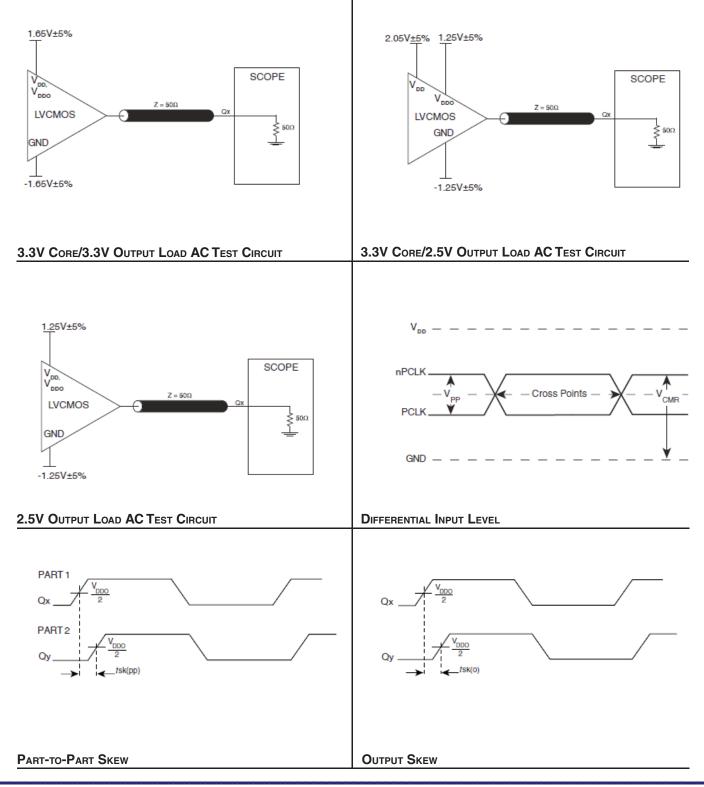
### Additive Phase Jitter

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the *dBc Phase Noise*. This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels (dBm) or a ratio of the power in the 1Hz band to the power in the fundamental. When the required offset is specified, the phase noise is called a *dBc* value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.



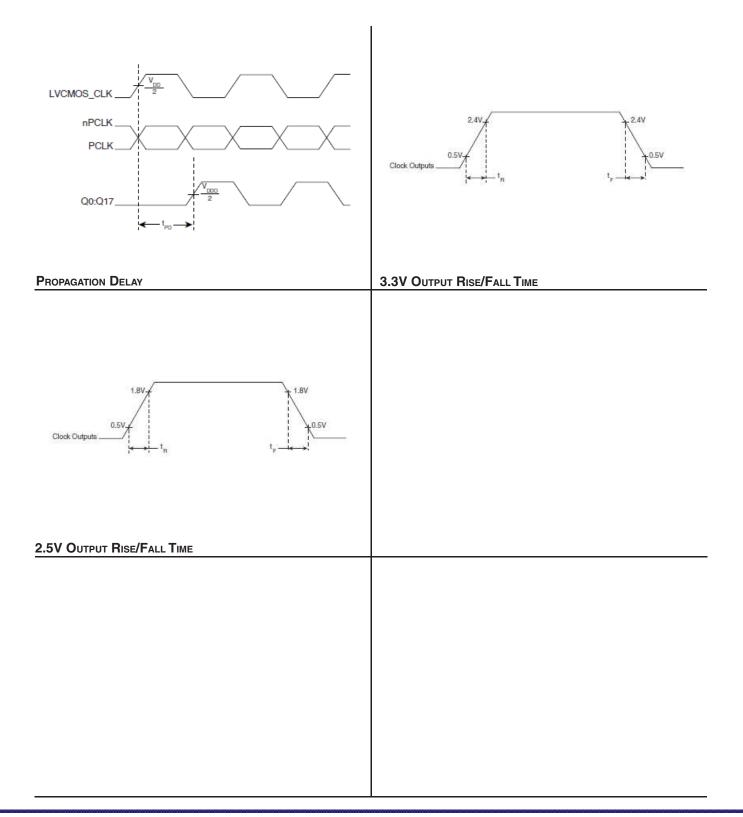
**OFFSET FROM CARRIER FREQUENCY (Hz)** 

As with most timing specifications, phase noise measurements have issues. The primary issue relates to the limitations of the equipment. Often the noise floor of the equipment is higher than the noise floor of the device. This is illustrated above. The device meets the noise floor of what is shown, but can actually be lower. The phase noise is dependant on the input source and measurement equipment.



## **PARAMETER MEASUREMENT INFORMATION**

LOW SKEW, 1-TO-18 LVPECL-TO-LVCMOS / LVTTL FANOUT BUFFER

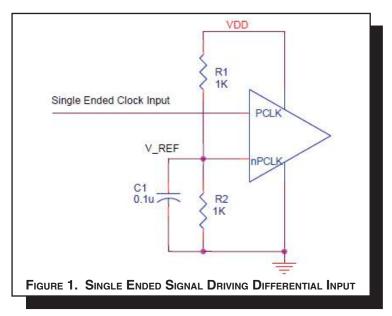


## **APPLICATION** INFORMATION

#### WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

*Figure 1* shows how the differential input can be wired to accept single ended levels. The reference voltage V\_REF =  $V_{DD}/2$  is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio

of R1 and R2 might need to be adjusted to position the V\_REF in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and  $V_{\text{DD}}$  = 3.3V, V\_REF should be 1.25V and R2/R1 = 0.609.



### LVPECL CLOCK INPUT INTERFACE

The PCLK /nPCLK accepts LVPECL, CML, SSTL and other differential signals. Both V<sub>SWING</sub> and V<sub>OH</sub> must meet the V<sub>PP</sub> and V<sub>CMR</sub> input requirements. *Figures 2A to 2F* show interface examples for the PCLK/nPCLK input driven by the most common driver types. The input interfaces suggested here are examples

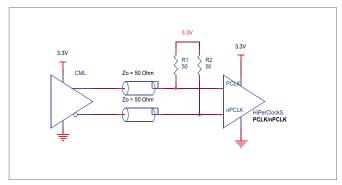


FIGURE 2A. PCLK/nPCLK INPUT DRIVEN BY AN OPEN COLLECTOR CML DRIVER

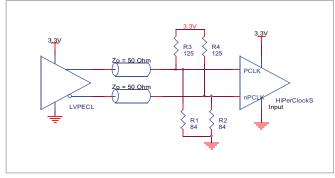


FIGURE 2C. PCLK/nPCLK INPUT DRIVEN BY A 3.3V LVPECL DRIVER

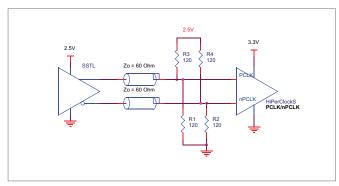


FIGURE 2E. PCLK/nPCLK INPUT DRIVEN BY AN SSTL DRIVER

only. If the driver is from another vendor, use their termination recommendation. Please consult with the vendor of the driver component to confirm the driver termination requirements.

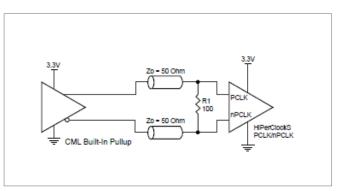


FIGURE 2B. PCLK/nPCLK INPUT DRIVEN BY A BUILT-IN PULLUP CML DRIVER

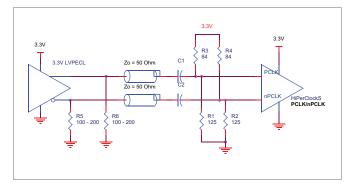
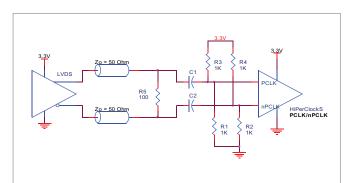


FIGURE 2D. PCLK/nPCLK INPUT DRIVEN BY A 3.3V LVPECL DRIVER WITH AC COUPLE





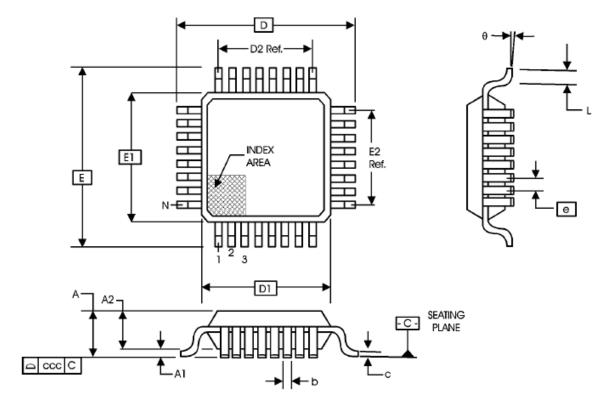
## **R**ELIABILITY INFORMATION

## TABLE 6. $\boldsymbol{\theta}_{JA} \text{vs.}$ Air Flow Table for 32 Lead LQFP

	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	67.8°C/W	55.9°C/W	50.1°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	47.9°C/W	42.1°C/W	39.4°C/W

#### TRANSISTOR COUNT

The transistor count for 83940D is: 820



PACKAGE OUTLINE - Y SUFFIX FOR 32 LEAD LQFP

TABLE 7. PACKAGE DIMENSIONS

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS					
0/4/201	BBA				
SYMBOL	MINIMUM	NOMINAL	MAXIMUM		
N		32			
Α			1.60		
A1	0.05		0.15		
A2	1.35	1.40	1.45		
b	0.30	0.37	0.45		
С	0.09		0.20		
D	9.00 BASIC				
D1	7.00 BASIC				
D2	5.60 Ref.				
E	9.00 BASIC				
E1	7.00 BASIC				
E2	5.60 Ref.				
е	0.80 BASIC				
L	0.45	0.60	0.75		
θ	0°		7°		
ccc			0.10		
Reference Document: JEDEC Publication 95, MS-026					

Reference D

#### TABLE 8. ORDERING INFORMATION

Part/Order Number	Marking	Package	Shipping Pack- aging	Temperature
83940DYLF	ICS83940DYLF	32 Lead "Lead Free" LQFP	Tray	0°C to 70°C
83940DYLFT	ICS83940DYLF	32 Lead "Lead Free" LQFP	Tape and Reel	0°C to 70°C

REVISION HISTORY SHEET						
Rev	Table	Page	Description of Change	Date		
	T5A	4	<ul> <li>3.3V AC Characteristics table -</li> <li>tsk(pp) Test Conditions, replaced "&lt;" with " ≤ "; corrected Units to "ns" from "ps".</li> <li>odc - corrected Test Conditions to read "134MHz ≤ f ≤ 250MHz", from "f ≤ 250MHz".</li> </ul>			
A	T5B	5	3.3V/2.5V AC Characteristics table - tsk(pp) Test Conditions, replaced "<" with " $\leq$ "; corrected Units to read "ns" from "ps".	10/11/02		
	T5C	6	2.5V AC Characteristics table - tsk(pp) Test Conditions, replaced "<" with " $\leq$ "; corrected Units to "ns" from "ps".			
		2	<ul> <li>Pin Characteristics table - changed R<sub>OUT</sub> 25Ω maximum to 28Ω maximum.</li> <li>Delete R<sub>PULLUP</sub> row.</li> <li>3.3V Output Load AC Test Circuit diagram - corrected GND equation to read</li> </ul>			
A	T2	7	-1.65V from -1.165V Added LVTTL to title. Updated format.	12/12/02		
в	T1 T2 T5A T5B T5C	2 2 4 5 6 7 10 11	Pin Description Table - added Pullup and Pulldown to Pin 6, nPCLK. Pin Characteristics Table - added R <sub>PULLUP</sub> row. Added tjit row. Added tjit row. Added tjit row. Added Additive Phase Jitter section. Updated Single Ended Signal Driving Differential Input diagram. Added LVPECL Clock Interface section.	10/9/03		
В	T5A - T5C	1 4 - 6 11 14	Added "Lead-Free" bullet to Features section. Added NOTE 7. Updated LVPECL Clock Input Interface section. Ordering Information table - added "Lead-Free" part number.	6/15/04		
В	Т8	14 16	Updated datasheet's header/footer with IDT from ICS. Removed ICS prefix from Part/Order Number column. Added Contact Page.	8/9/10		
В	Т8	14	Ordering Information - Removed leaded devices. Updated data sheet format.	3/25/15		



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